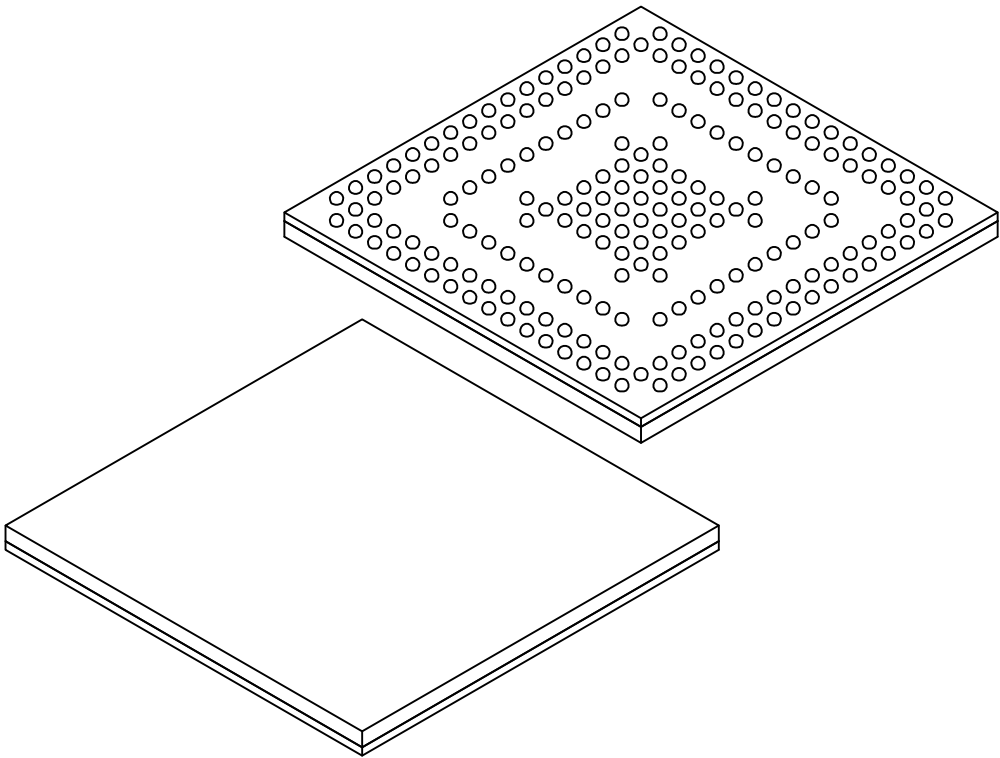


## 208-Ball Fine-Pitch Ball Grid Array Package (8MX) - 15x15x1.19 mm Body [TFBGA]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	208		
Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.19
Ball Height	A1	0.21	0.30	–
Mold Thickness	A2	0.48	0.53	0.58
Overall Length	D	15.00 BSC		
Ball Array Length	D2	13.60 BSC		
Overall Width	E	15.00 BSC		
Ball Array Width	E2	13.60 BSC		
Ball Diameter	b	0.35	0.40	0.45

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M  
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.  
 REF: Reference Dimension, usually without tolerance, for information purposes only.